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International Bureau

INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification 6 : H01L 23/498, 23/538, G06K 19/077 — A1

(11) International Publication Number: WO 96/37917

(43) International Publication Date: 28 November 1996 (28.11.96)

(21) International Application Number: PCT/JP96/01348

(22) International Filing Date: 22 May 1996 (22.05.96)

(30) Priority Data:
7/123574 — 23 May 1995 (23.05.95) — JP

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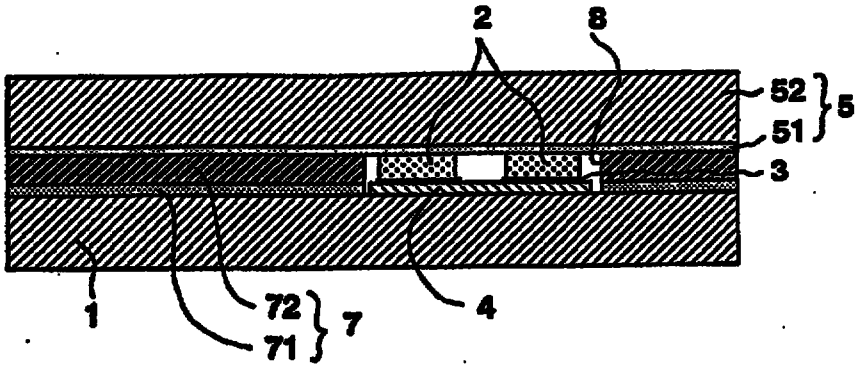
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(81) Designated States: AU, CA, CN, NO, SG, US, European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).

Published
With international search report.
Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.

(54) Title: SEMICONDUCTOR ASSEMBLY



(57) Abstract

Provided is a semiconductor assembly, comprising a circuit board (1) including a conductor circuit (4), the conductor circuit including connecting pads, a semiconductor chip (2) provided with connecting terminals provided on a first surface thereof, and mounted on the circuit board, a casing (5) covering the circuit board, wherein the connecting pads of the conductor circuit and the connecting terminals of the semiconductor chip are disposed in mutually opposing relationship, and are connected with each other by an electroconductive bonding agent, a neutral plane of the semiconductor chip substantially coinciding with an overall neutral plane of the semiconductor assembly.